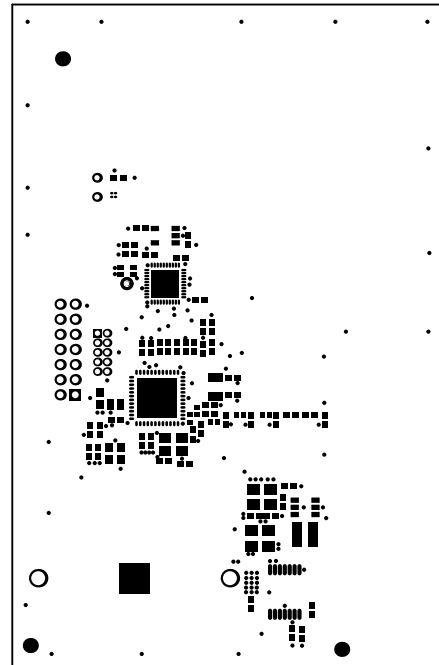
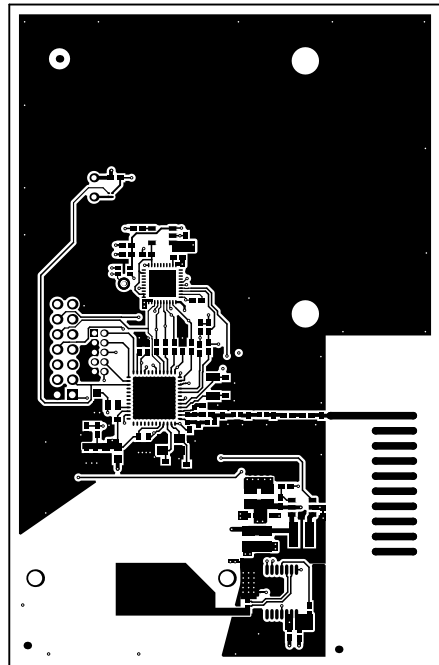


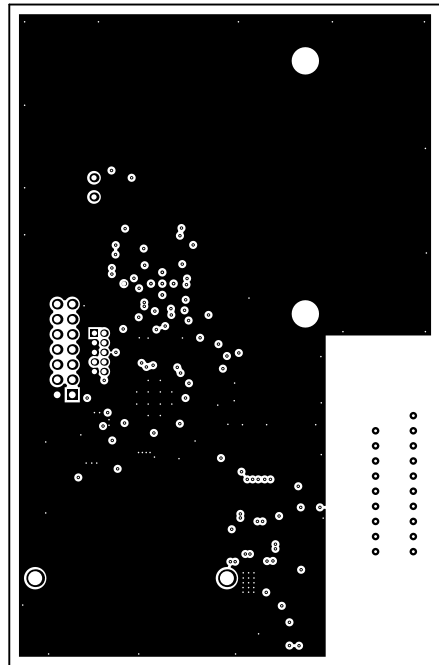
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01236	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01236		
PLOT NAME = Top Overlay	GENERATED : 1/6/2017	1:01:17 PM	TEXAS INSTRUMENTS



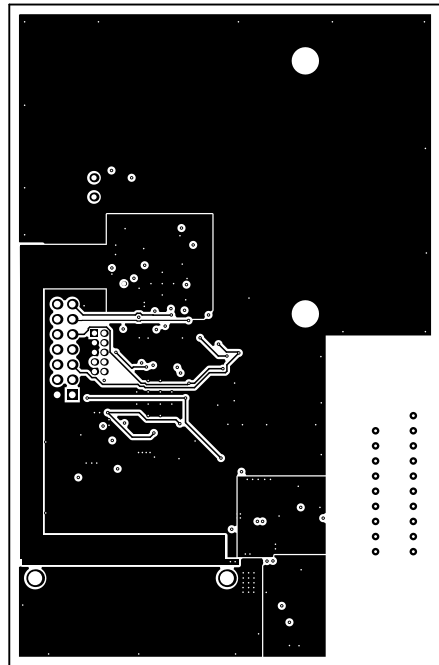
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01236	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01236		
PLOT NAME = Top Solder Mask	GENERATED : 1/6/2017 1:01:18 PM	TEXAS INSTRUMENTS	



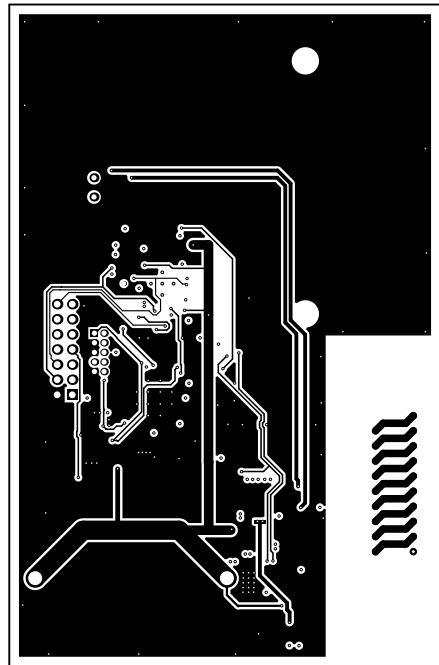
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01236	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01236		
PLOT NAME = Top Layer	GENERATED : 1/6/2017 1:01:19 PM	TEXAS INSTRUMENTS	



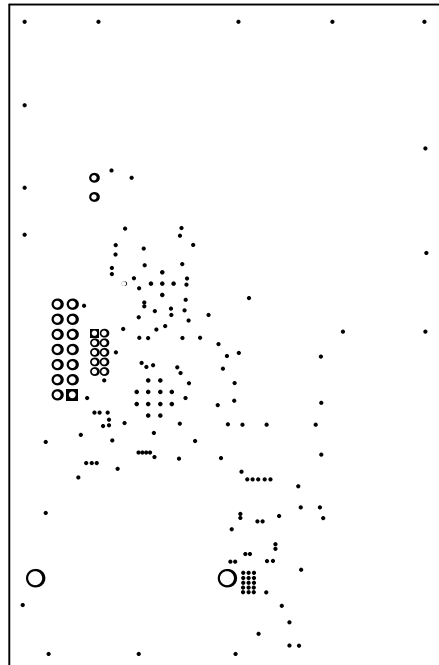
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01236	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01236		
PLOT NAME = Signal Layer 1	GENERATED : 1/6/2017 1:01:20 PM	TEXAS INSTRUMENTS	



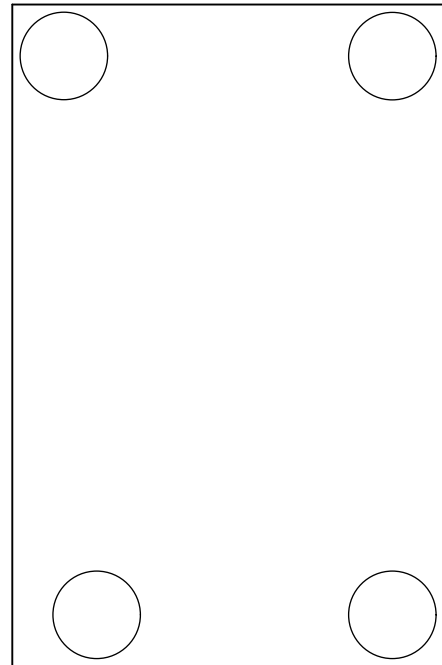
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01236	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01236		
PLOT NAME = Signal Layer 2	GENERATED : 1/6/2017	1:01:20 PM	TEXAS INSTRUMENTS



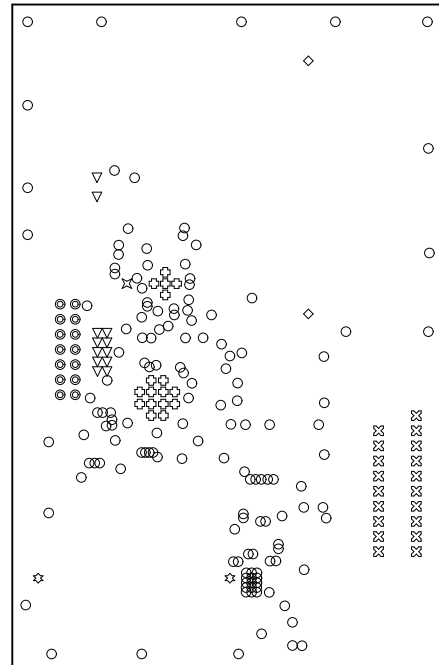
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01236	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01236		
PLOT NAME = Bottom Layer	GENERATED : 1/6/2017 1:01:21 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01236	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01236		
PLOT NAME = Bottom Solder Mask	GENERATED : 1/6/2017	1:01:22 PM	TEXAS INSTRUMENTS

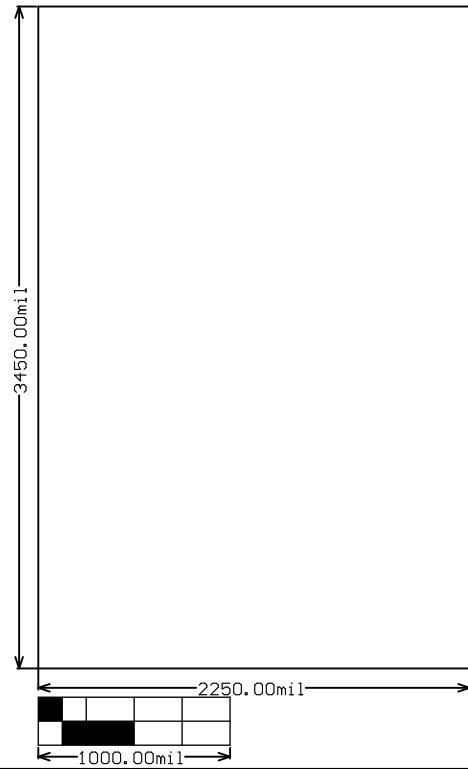


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01236	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01236		
PLOT NAME = Bottom Overlay	GENERATED : 1/6/2017	1:01:23 PM	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊠	1	23.62mil (0.600mm)	NPTH	Round	Top Layer - Bottom Layer	
◇	2	118.11mil (3.000mm)	NPTH	Round	Top Layer - Bottom Layer	
⊕	17	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
○	148	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	19	14.96mil (0.380mm)	PTH	Round	Top Layer - Bottom Layer	
▽	12	27.56mil (0.700mm)	PTH	Round	Top Layer - Bottom Layer	
●	14	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
☆	2	72.83mil (1.850mm)	PTH	Round	Top Layer - Bottom Layer	
215 Total						

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01236	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01236		
PLOT NAME = Drill Drawing	GENERATED : 1/6/2017	1:01:24 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01236	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01236		
PLOT NAME = Board Dimensions	GENERATED : 1/6/2017	1:01:24 PM	TEXAS INSTRUMENTS

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